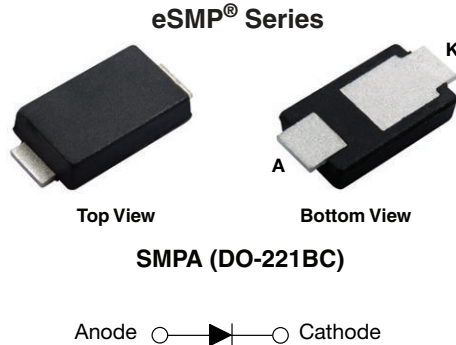


Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier



FEATURES

- Very low profile - typical height of 0.95 mm
- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Automotive ordering code: P/NHM3
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8.0 A
V_{RRM}	200 V
I_{FSM}	100 A
V_F at $I_F = 8.0$ A ($T_A = 125$ °C)	0.70 V
T_J max.	175 °C
Package	SMPA (DO-221BC)
Circuit configuration	Single

TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial and automotive applications.

MECHANICAL DATA

Case: SMPA (DO-221BC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	V8PA22	UNIT
Device marking code		V822	
Maximum repetitive peak reverse voltage	V_{RRM}	200	V
Maximum DC forward current	$I_{F(AV)}^{(1)}$	8.0	A
	$I_{F(AV)}^{(2)}$	2.4	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	100	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	T_{STG}	-40 to +175	°C

Notes

(1) Mounted on 3 cm x 3 cm copper pad area PCB

(2) Free air, mounted on recommended copper pad area

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 4.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.77	-	V
				$I_F = 8.0\text{ A}$	0.84	
	$I_F = 4.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.62	-	
				$I_F = 8.0\text{ A}$	0.70	
Reverse current	$V_R = 160\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.001	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.5	-	
	$V_R = 200\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.10	
		$T_A = 125\text{ }^\circ\text{C}$		1.0	7.0	
Typical junction capacitance	4.0 V, 1 MHz		C_J	400	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
 (2) Pulse test: Pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)			
PARAMETER	SYMBOL	V8PA22	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	100	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	5	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
 (2) Free air, mounted on recommended copper pad area; thermal resistance $R_{\theta JA}$ - junction to ambient
 (3) Units mounted on 3 cm x 3 cm aluminum PCB; thermal resistance $R_{\theta JM}$ - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V8PA22-M3/H	0.032	H	3500	7" diameter plastic tape and reel
V8PA22-M3/I	0.032	I	14 000	13" diameter plastic tape and reel
V8PA22HM3/H ⁽¹⁾	0.032	H	3500	7" diameter plastic tape and reel
V8PA22HM3/I ⁽¹⁾	0.032	I	14 000	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

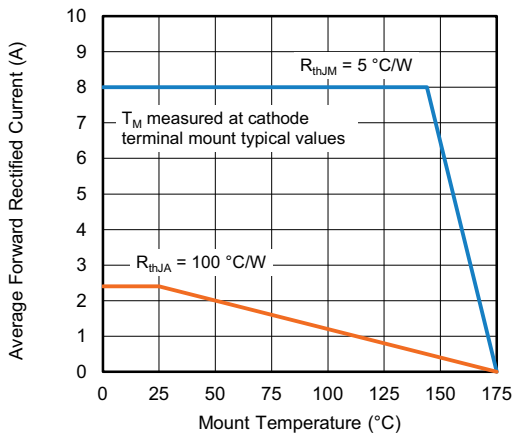
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)


Fig. 1 - Maximum Forward Current Derating Curve

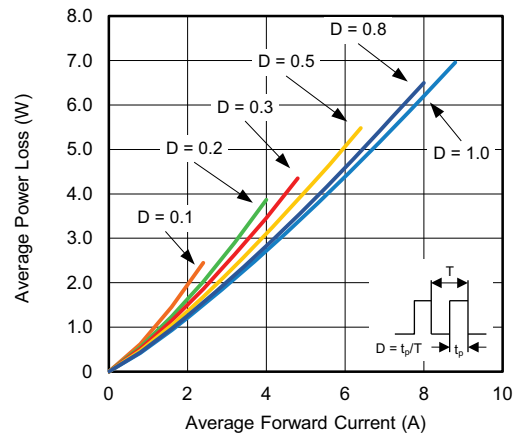


Fig. 2 - Forward Power Loss Characteristics

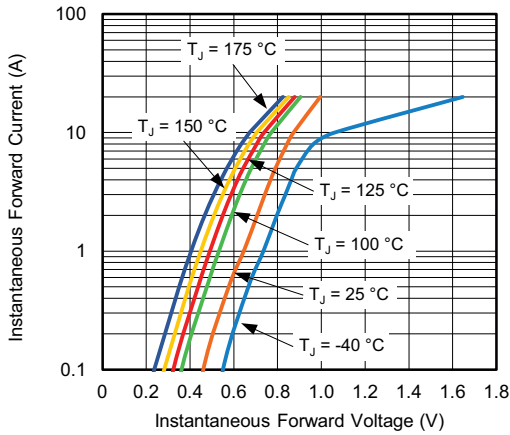


Fig. 3 - Typical Instantaneous Forward Characteristics

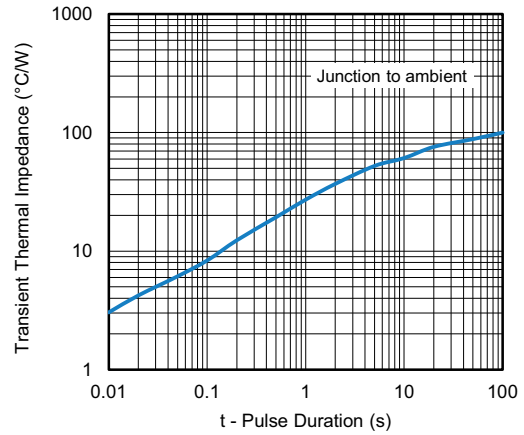


Fig. 6 - Typical Transient Thermal Impedance

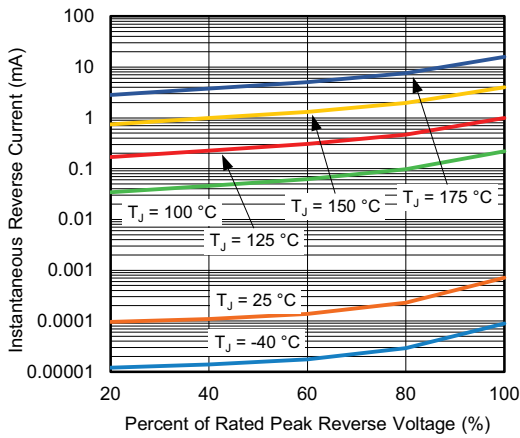


Fig. 4 - Typical Reverse Leakage Characteristics

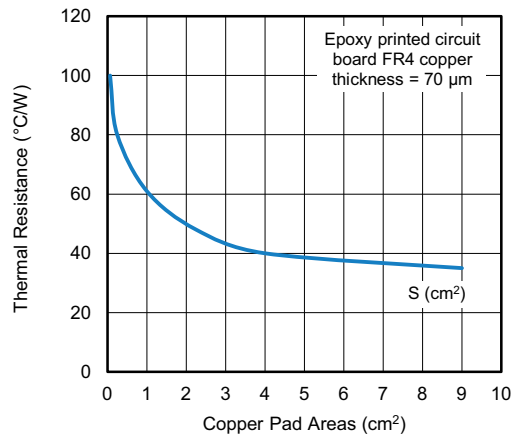


Fig. 7 - Thermal Resistance Junction to Ambient vs. Copper Pad Areas

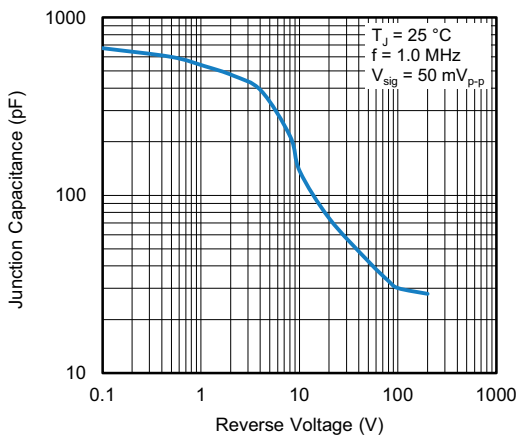
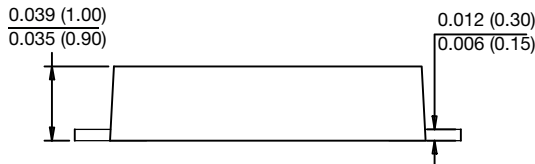
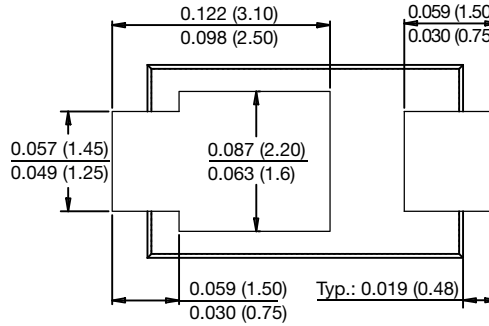
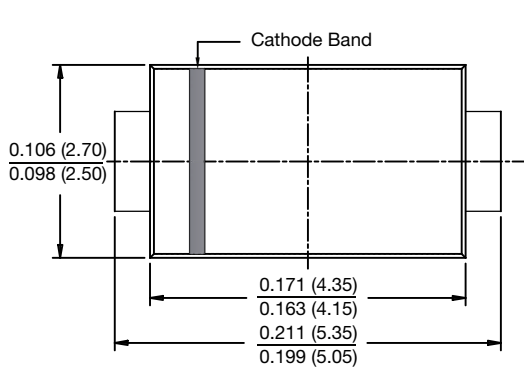


Fig. 5 - Typical Junction Capacitance

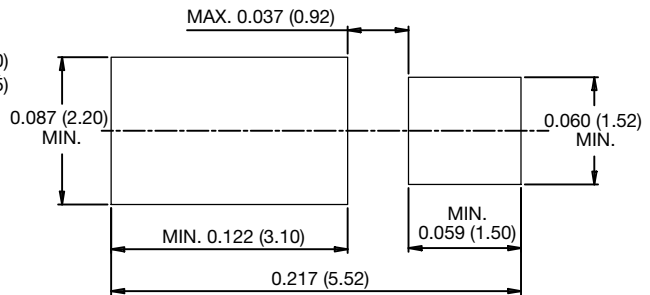


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPS (DO-221BC)



Mounting Pad Layout





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